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- 15. The barrier assembly of claim 14 wherein the rigid substrate material is selected from ceramics, metals, and semiconductors.
- **16**. The barrier assembly of claim **1** wherein at least one of the at least one polymer layers comprises an acrylate- 5 containing polymer.
- 17. The barrier assembly of claim 4 further comprising a polymer smoothing layer adjacent to the substrate.
- 18. The barrier assembly of claim 4 further comprising a scratch resistant layer adjacent to the substrate.
- 19. The barrier assembly of claim 4 further comprising an anti-reflective coating adjacent to the substrate.
- 20. The barrier assembly of claim 4 further comprising an anti-fingerprint coating adjacent to the substrate.

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21. The barrier assembly of claim 4 further comprising an anti-static coating adjacent to the substrate.

22. The barrier assembly of claim 1 wherein the at least one barrier layer comprises two barrier layers.

23. The barrier assembly of claim 22 wherein the two barrier layers are made of the same barrier material.

24. The barrier assembly of claim 22 wherein the two barrier layers are made of different barrier materials.

25. The barrier assembly of claim 11 wherein at least one of the at least one barrier layers is opaque cermet selected from zirconium nitride, titanium nitride, hafnium nitride, tantalum nitride, niobium nitride, tungsten disilicide, titanium diboride, and zirconium diboride.

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